

More Moore's Law through Computational Scaling -- and EDA's Role

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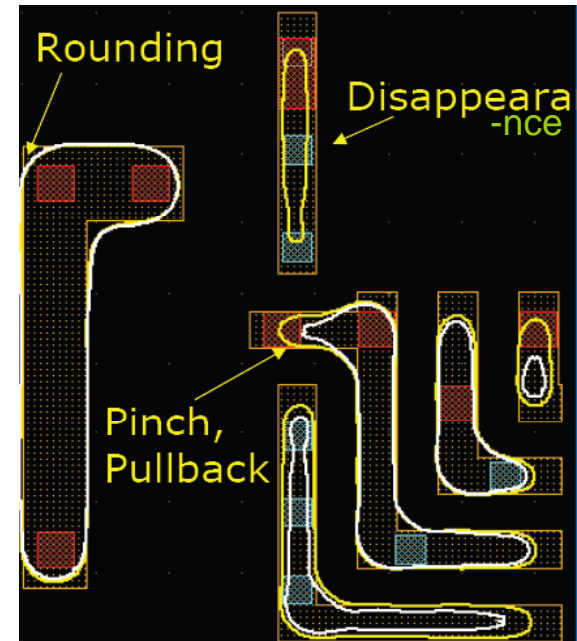
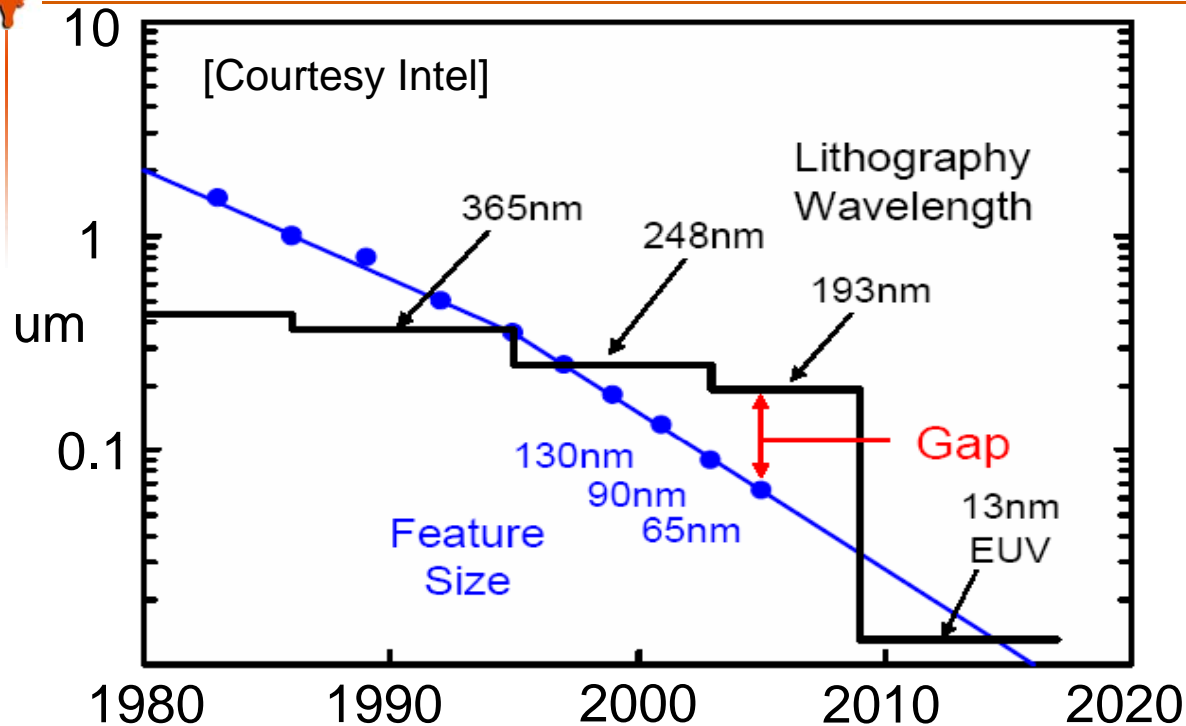
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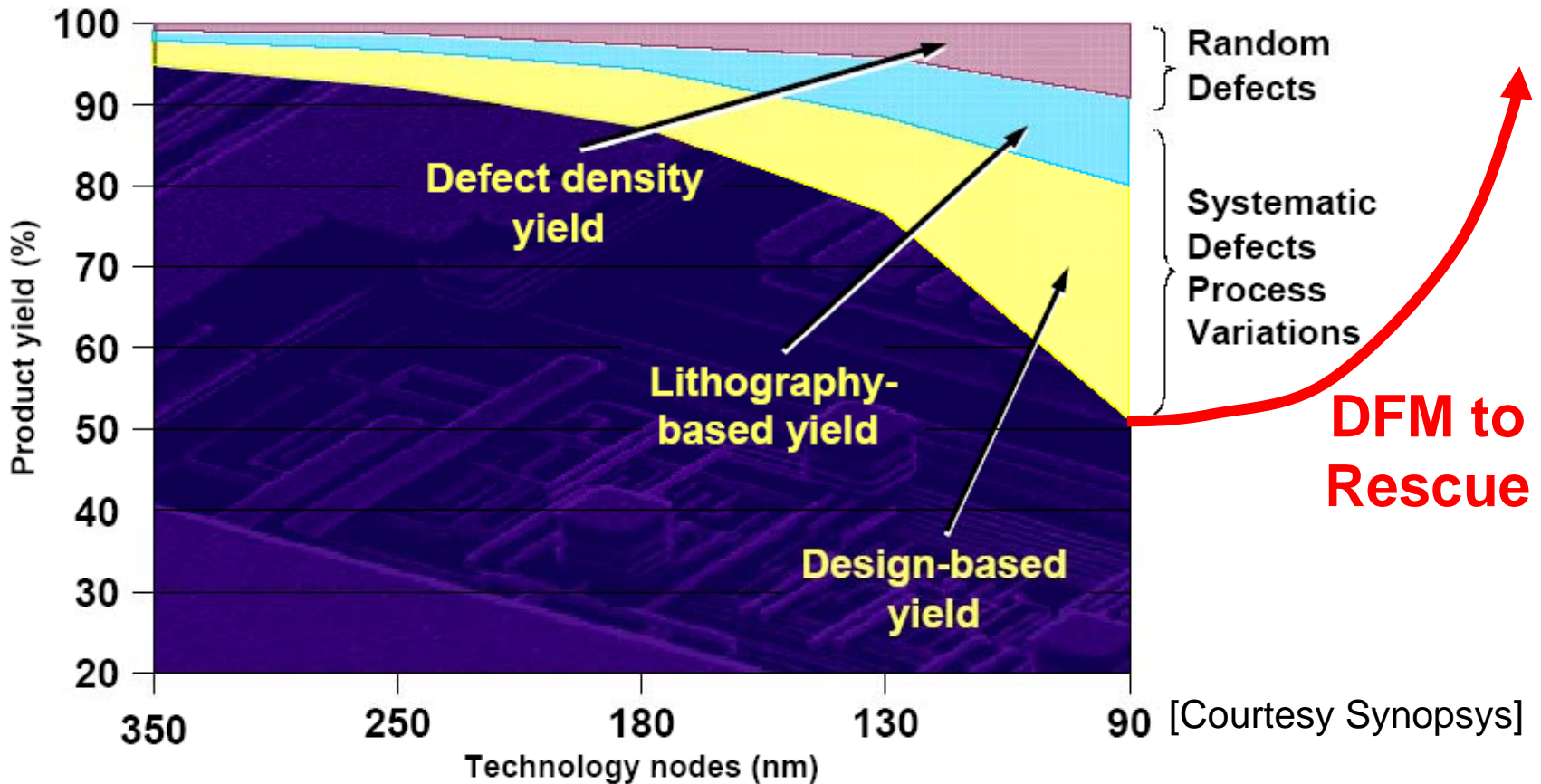
<http://www.cerc.utexas.edu/utda>

Scaling & Lithography Status



- ◆ 193nm litho continues to push its limit
 - › Immersion, extreme RET, DPL (Double Patterning Lithography)
- ◆ NGL - Next Generation Lithography, **still next generation**
 - › Economical/material/technical challenges

A Famous (or Infamous?) Projection

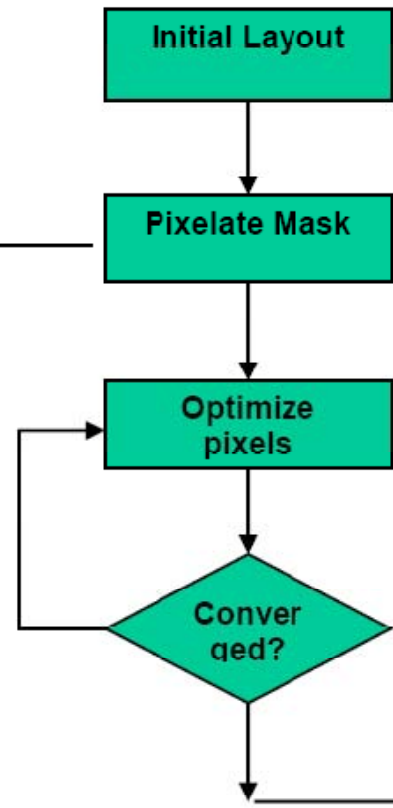
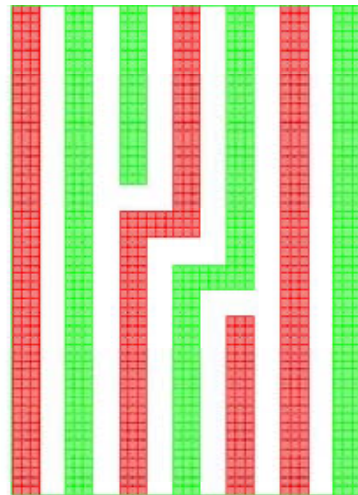


- ◆ Scaling, though challenged, still pushing!
- ◆ But more important role in computational scaling

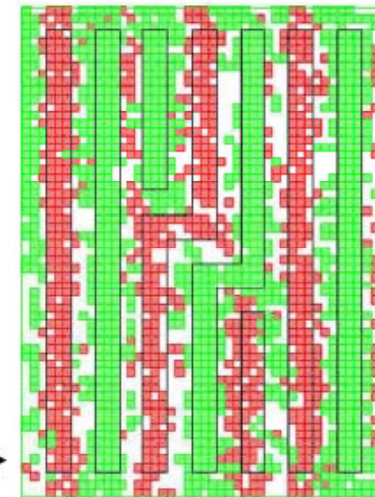
Computational Scaling

- ◆ Not just by equipment advancement
- ◆ Computational scaling
 - › Scaling enabled by massive computational power
 - › Fast computers to help design faster computers
- ◆ **Computational lithography** for nanolithography systems
 - › Computationally reverse-engineering
- ◆ **Electronic design automation (EDA) eco-system** to close the gaps
 - › Synergistic Process-Layout-Circuit Co-Optimization
 - › Parallel, multi-core, GPU, domain-specific, FPGA...

Computational Lithography



Intel's Pixelated Mask
[Singh+, SPIE'08)



◆ Other examples:

- › Variational litho-modeling [Yu+, DAC'06, JM3'07]
- › IBM: source mask optimization

Computational Nanolithography

- ◆ We do have massive computational power!
 - › IBM BlueGene, Brion/ASMLTachyon (FPGA acceleration), Gauda (leveraging cheap GPU), ...
- ◆ Make a trillion pixels dance [Singh+, SPIE'08]

Still

There's Plenty of Room at the Bottom

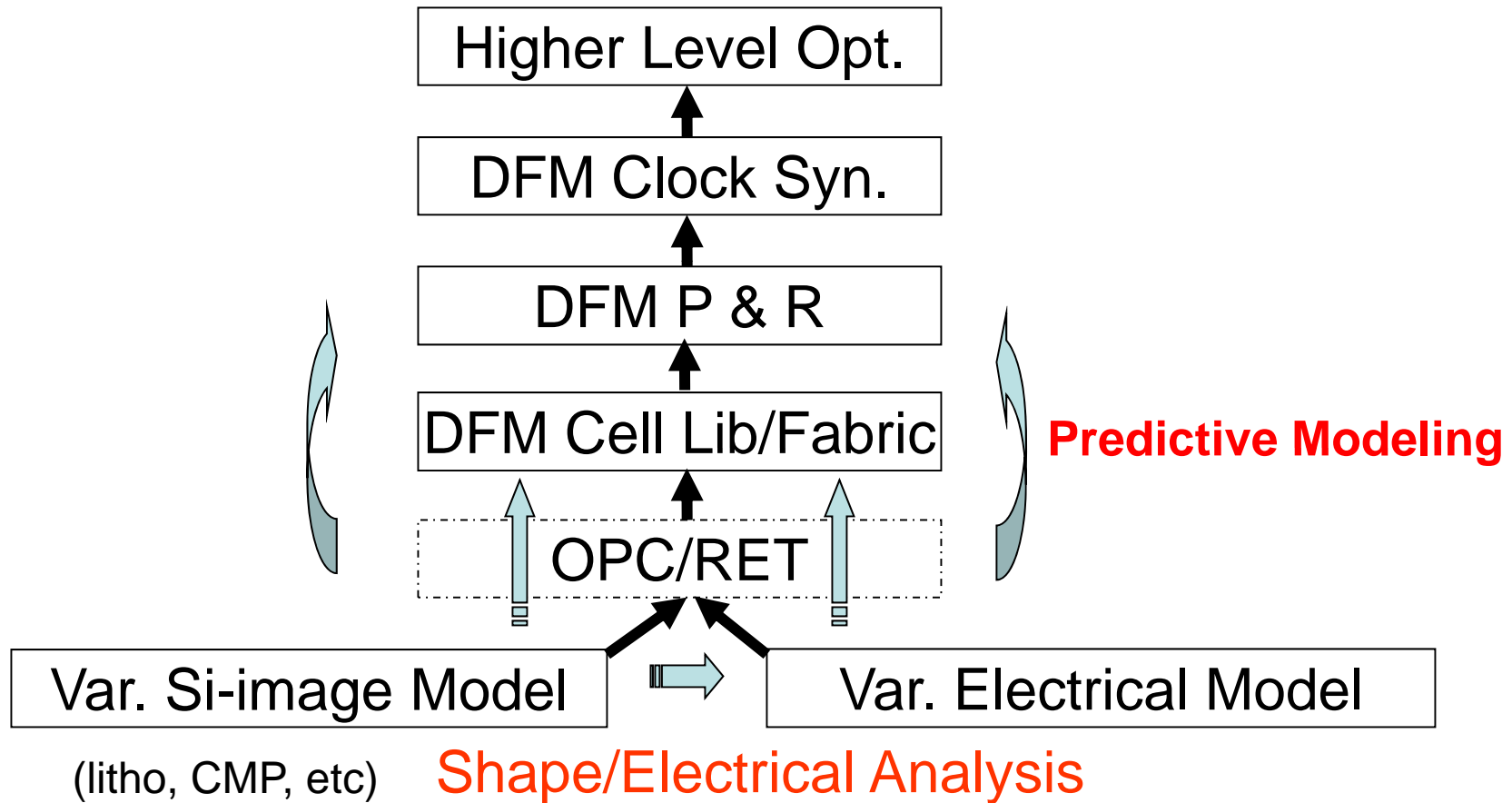
- An Invitation to Enter a New Field of Physics



Richard P. Feynman, 1959

Synergistic Process-Layout-Ckt Co-Opt

Shape/Electrical Optimization



Synergistic Optimizations



“(

he

“Give me a lever, and I can optimize your billion transistor design.” - EDA’s Lever (model/rule)

Process Modeling

◆ How complicated?

$$I_I(x_1, y_1) = \iiint J_0(x_0 - x'_0, y_0 - y'_0) F(x_0, y_0) F^*(x'_0, y'_0) \\ \times K(x_1 - x_0, y_1 - y_0) K^*(x_1 - x'_0, y_1 - y'_0) dx_0 dy_0 dx'_0 dy'_0$$

**Litho model:
Hopkins eqn**

◆ or simple can it be?

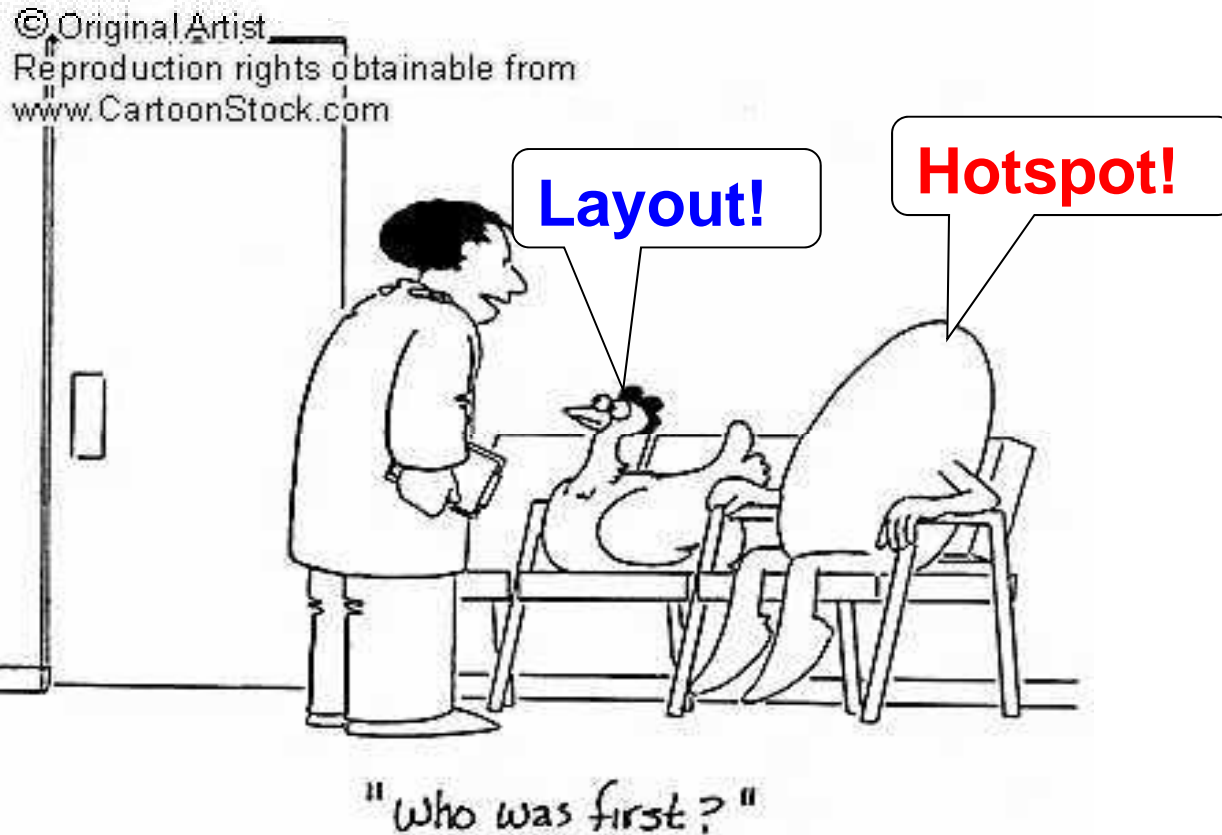
$$Cu_Thickness = \alpha * \left(1 - \frac{Metal_density^2}{\beta}\right)$$

**CMP model:
[Cho+, ICCAD'06]**

◆ Key Issues:

- › Accuracy vs. Fidelity (Elmore-like)
- › Design-oriented vs. process-oriented

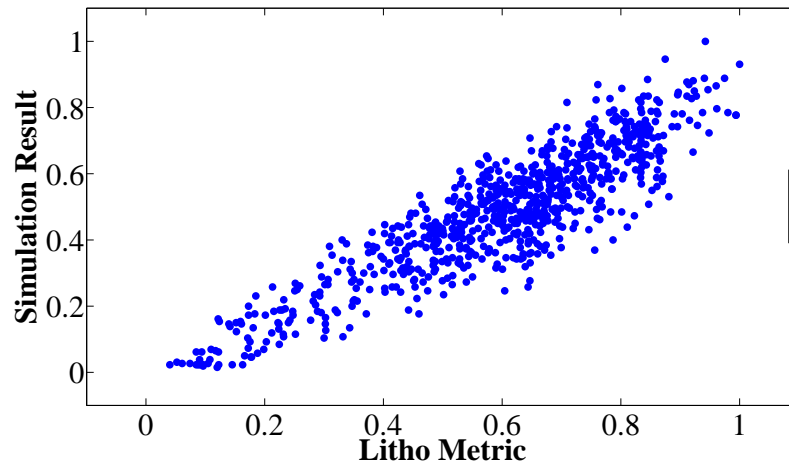
Prediction & Prescription



- ◆ **Prediction: e.g., statistical modeling [Cho+, DAC'08], machine learning [Ding+, ICICDT'09]**
- ◆ **Prescription: only work with patterns that are printable**

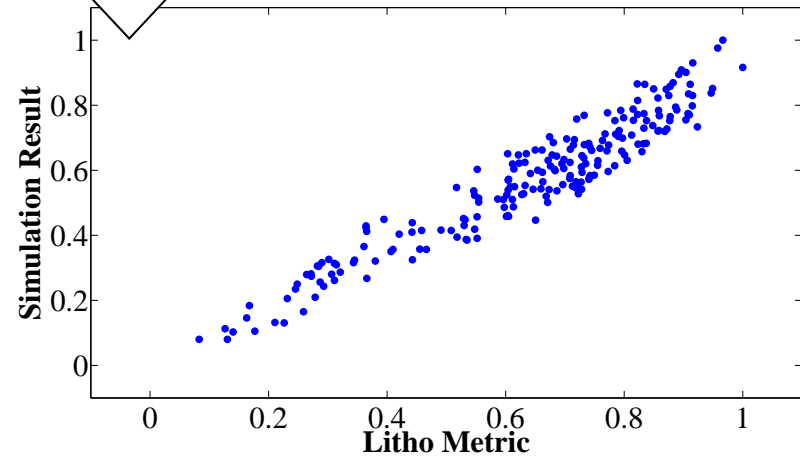
E.g., Post-OPC Predictive Modeling

[Cho+, DAC'08]



R=0.90, 16x16um²

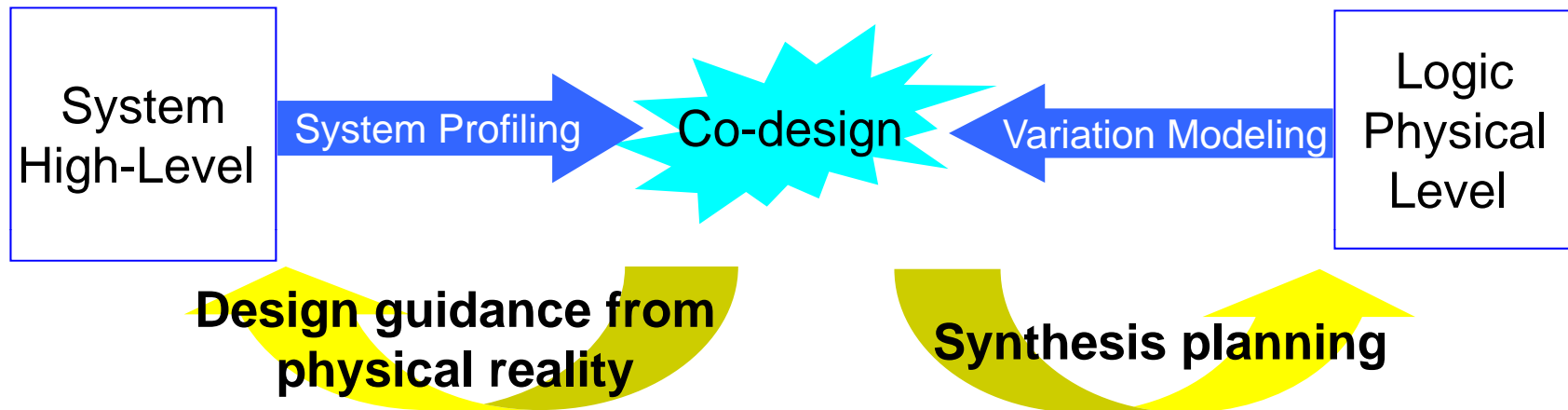
**Higher correlation
in more macro level,**



R=0.95, 32x32um²

◆ **Very high macro-level fidelity**

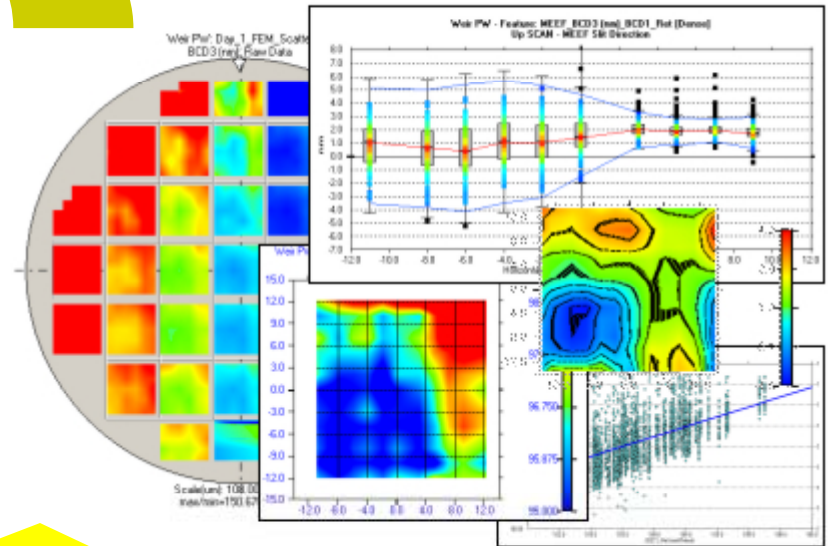
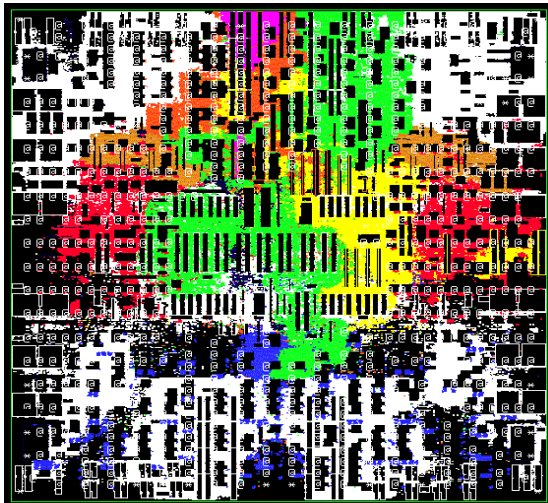
Moving Up: System/High-Level and Logic/Physical-Level Co-design



- ◆ Variation budgeting with system-level profiling

Moving Down: Design for Equipment

Equipment Characteristics

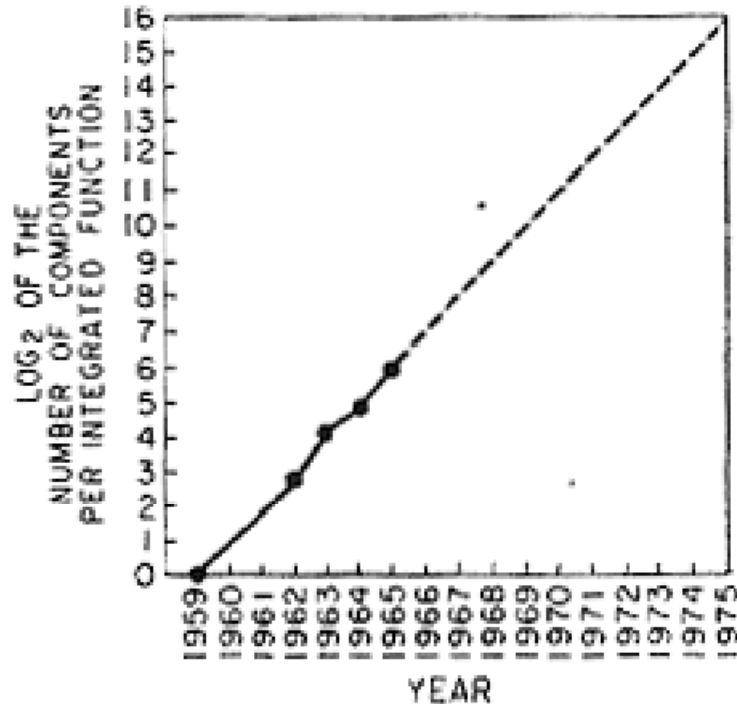


Tunable Parameters

- ◆ Timing optimization using ASML dose mapper [Jeong, Kahng+ DAC'08]
- ◆ Combine DFM and APC (advanced process control) [Pan+, JPC'08]

The Moore, The Better

- ◆ There is still plenty of life for Moore's Law
- ◆ **Bigger role of Computational Scaling and EDA** to extend the Moore's Law



[Moore 1965]

- ◆ **NO EXPONENTIAL IS FOREVER...**
- ◆ **BUT**
- ◆ **WE CAN DELAY "FOREVER"**

Moore's Law Amendment
[Moore 2003]